

ABSTRACT OF THE DISCLOSURE

A thermal head of the present invention is provided with a thermal insulation layer formed on a radiative substrate, a plurality of heating resistors formed on a top face of the thermal insulation layer, a plurality of power suppliers connected to the heating resistors to form a heater on a part of the heating resistors, and a protection layer that covers surfaces of at least the heating resistors and the power suppliers, wherein the thermal insulation layer is formed by laminating an inorganic high thermal insulation layer including a complex oxide ceramic containing Si, transition metal, and oxygen or including complex nitride ceramic containing Si, transition metal, and nitrogen on an organic thermal insulation layer that contains polyimide resin.